

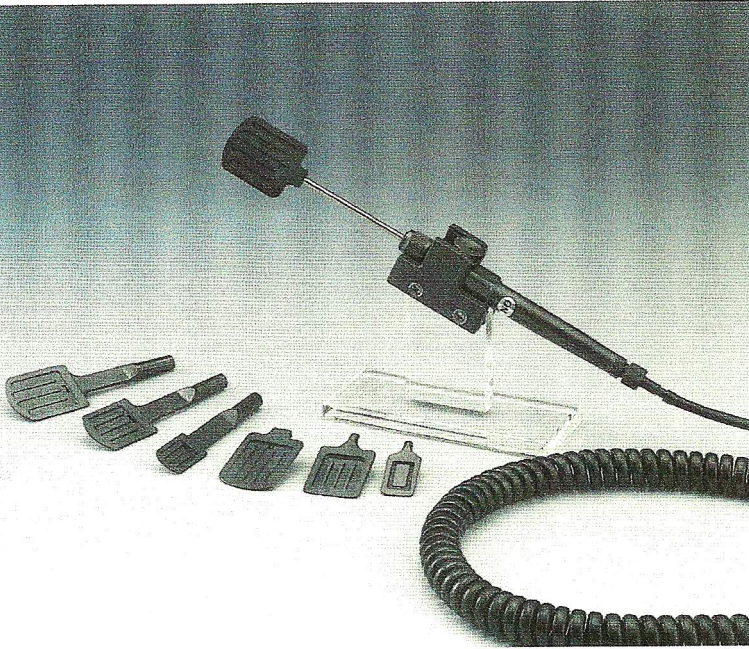
Vacuum Wand

Features

- Our unique valve* ensures reliable suction and release of a wafer/die.
- The well polished inner wall of the valve part minimizes particle generation.
- The optically polished wafer tip provides excellent adhesion to a wafer.
- The wand body can be easily detached from the tubing.
- A large selection of attachments for die handling are available.

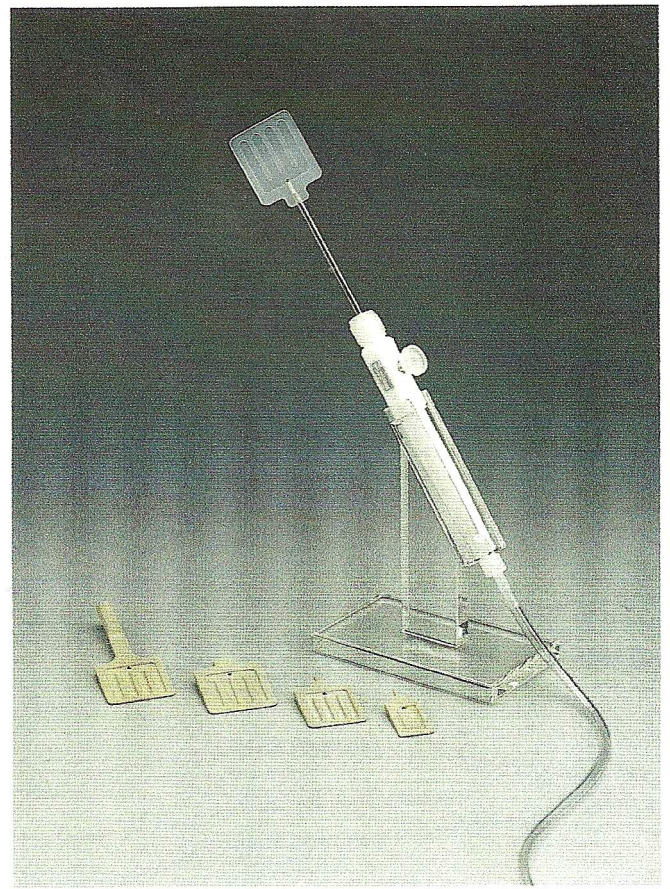
* US Patent 4767142, Japanese Patents 1698352 and 1885465

ESD protection



- The body covered with conductive nylon reduces electrostatic effects towards a wafer.
- The wafer tip is made of conductive PEEK.
- The resistance value of 10^6 to $10^8 \Omega$ provides optimum static protection.

Teflon® body



- The body is made of Teflon® for chemical resistance.
- A large selection of wafer tips are available.